APPLICA	BLE STAN	DARD										
Operating temperature range			-55 °C to 125 °C (n	ote 1)	Storage temperature range			-10°C TO 60°C(Packed condition)				
RATING	Voltage Current		50V AC/DC		Operating or storage humidity range		ge	Relative humidity 90 % MAX (Not dewed				
					Applica (FPC/F			t=0.3±0.05mm, Gold (Ground plate : Tin				
			SPEC	IFICA	1OITA	NS						
IT	EM		TEST METHOD				REG	QUIF	REMENTS	QT	АТ	
CONSTRUCTION												
General exa	General examination Vis					According to drawing.				×	×	
Marking		Confirme	d visually.			(note 2	2)			×	×	
	ICAL CHA											
Voltage proof		150 V AC for 1 min.				No flashover or breakdown.				×	_	
Insulation re	sistance	100 V DC.				500 Mg	Ω MIN.			×	-	
Contact resis	stance	AC 20 mV MAX , 1 mA .				100 mg	Ω MAX.			×	1 —	
							Including FPC/FFC bulk resistance (L=8mm(FPC) , 20mm(FFC))					
MECHAN	NICAL CHA	RACTE	RISTICS									
Vibration			y 10 to 55 Hz, half amplitud			_			ntinuity of 1 µs.	×	_	
Shock		0.75 mm, for 10 cycles in 3 axial directions. 981 m/s ² , duration of pulse 6 ms				② Contact resistance: 100 mΩ MAX.③ No damage, crack and looseness of parts.			. ×	_		
		at 3 times in 3 both axial directions. 10 times insertions and extractions.				① Contact resistance: 100 mΩ MAX.			×	 		
								crack and looseness of parts.				
FPC/FFC insertion/extraction force FPC/FFC		Measured by applicable FPC/FFC. (Thickness of FPC/FFC shall be t=0.3mm at initial condition.) Measured by applicable FPC/FFC.			Insertion force: Direction of insertion (n: Number of contacts) 4+0.3×n N MAX (FPC/FFC) (note 3) 4+0.39×n N MAX (Shielded FFC) (note 3) Extraction force: Direction of extraction (n: Number of contacts) 8.5+0.16×n N MAX (FPC/FFC) (note 3) 8.5+0.2×n N MAX (Shielded FFC) (note 3) Direction of extraction			3)	_			
retention force		(Thickness of FPC/FFC shall be t=0.3mm at initial condition.)			(n : Number of contacts) 18+0.05×n N MIN (FPC/FFC) (note4) 7+0.11×n N MIN (Shielded FFC) (note4)				×			
ENVIRO	NMENTAL	CHARA	CTERISTICS						, , , ,			
temperature T		Temperature -40 \rightarrow +15 _{TO} +35 \rightarrow +125 \rightarrow +15 _{TO} +35 $^{\circ}$ C Time 30 \rightarrow 2 to 3 \rightarrow 30 \rightarrow 2 to 3 min			 Contact resistance: 100 mΩ MAX. Insulation resistance: 50 MΩ MIN. 			×	_			
		Under 5 cycles. Exposed at 60±2 °C,				③ No damage, crack and looseness of parts.						
- Jamp Hoat (cioday olalo)		numidity 90 to 95 %, 96 h.			İ				×	_	
Damp heat,cyclic		Relative I	Exposed at -10 to +65 °c, Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.			 Contact resistance: 100 mΩ MAX. Insulation resistance: 1 MΩ MIN. (At high humidity) Insulation resistance: 50 MΩ MIN. (At dry) No damage, crack and looseness of parts 			×	_		
COUN	IT DE	ESCRIPTIO	ON OF REVISIONS		DESIG	NED			CHECKED	D.F	DATE	
1 REMARK		DIS-F-00006186 KN. KO			KN. KOBA	BAYASHI APPROVI		HS. HIRAHARA			00615	
								ED HS. SAKAMOTO		2019	20190409 20190409	
			(IEO 00540							_		
					DESIGN				2019	90409		
Unless otherwise specified, refer to IEC 60512.				DRAWN NM. YONEYAMA			-	20190409				
Note QT:Q	ualification Te	st AT:Ass	surance Test X:Applicable 1	Гest	DF	DRAWING NO. ELC-388109-)0-0(0			
RS SPECIFICATION SHEET PAR			PART	NO. FH63S-**S-0. 5SH			1					
HIROSE ELECTRIC CO., LTD.					NO.							

	SPECIFICATI	ONS		
ITEM	TEST METHOD	REQUIREMENTS	QT	AT
Dry heat	Exposed at 125±2°C, 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Cold	Exposed at -55±3°C, 96 h.	② No damage, crack and looseness of parts	×	_
Sulphur dioxide [JIS C 60068-2-42]	Exposed at 40 ± 2 °C, Relative humidity $80\pm5\%$ 25 ± 5 ppm for 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Solderability	Soldered at solder temperature, 245±3°C for immersion duration,3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	_
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250 °C MAX. Reflow TMP. over 220 °C 60 to 90 sec. Number of reflow: 2 times 2) Soldering irons: TMP. 350±10 °C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (note 5)	×	_

(note 1)



The heat resistant temperature when using FFC is 105°C.

When the heat resistant temperature of FPC/FFC is less than 125°C/105°C, the heat resistant temperature of FPC/FFC is applied.

(note 2)

This product features bottom-contact point.

"One Action Lock" completes FPC/FFC lock just by inserting the FPC/FFC.

Do not operate the actuator when inserting the FPC/FFC.

(note 3)

Do not insert the FPC/FFC to this product at an angle.

(note 4)

Stabilize the FPC/FFC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC/FFC.

There's a case witch FPC/FFC retention force doesn't fulfill the value, because FPC/FFC specification affects the result of FPC/FFC retention force.

(note 5)

Blisters which may be generated on the housing do not affect product performance.

(note 6)

The occurrence and the length of whisker, and the performance deterioration caused by it are out of the scope of this specification

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-388109-00-00			
HRS	SPECIFICATION SHEET	PART NO.	FH63S-**S-0. 5SH				
11.0	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	A	2/2	